

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

- NOTES:
- MATERIAL:
 - HOUSING: HALOGEN FREE PLASTIC, HIGH TEMP., UL94V-0;
 - CONTACT: COPPER ALLOY
 - FINISH:
 - CONTACT:
 - 50~100u" NICKEL UNDERPLATING OVERALL.
 - 1:G/F PLATED ON CONTACT AND SOLDER TAIL AREA
 - N: 80~120u" MATT TIN PLATING
 - L: 100~200u" PURE TIN PLATING
 - T: 10u" Gold ON CONTACT AREA
 - SOLDER:
 - 50~100u" NICKEL UNDERPLATING OVERALL.
 - 1:G/F PLATED ON CONTACT AND SOLDER TAIL AREA
 - N: 80~120u" MATT TIN PLATING
 - L: 100~200u" PURE TIN PLATING
 - T: G/F PLATED ON SOLDER AREA
 - REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
 - SPEC. PLS. REFER TO PS-50305-xxxx
 - PACKAGE PLS. REFER TO PACKING TABLE

P/N LEGEND

50311-XXX X X-XXX

Others	Housing color&Material	HALOGEN FREE	DIM C	PACKING
001	BLACK&HTN	HF	2.0	88317-XXCR
002	BLACK&HTN	HF	2.5	88317-XXCR
003	BLACK&HTN	HF	3.0	88317-XXCR-07
004	NATURAL&LCP	HF	2.0	88317-XXCR
005	BLACK&HTN	HF	2.0	88317-XXCR-U
006	BLACK&HTN	HF	3.0	50311-TB

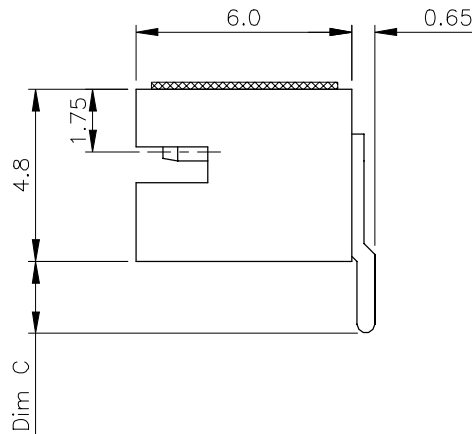
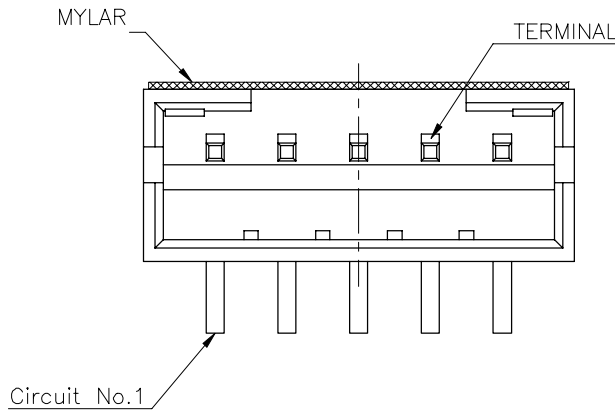
CKTS

PACKING

- 0:TAPE & REEL
- 1:Tube
- 4:TAPE & REEL WITH MYLAR
- 5:Tube WITH MYLAR

- PLATING
- 1:G/F PLATED ON CONTACT AND SOLDER TAIL AREA
 - L:100~200u"PURE TIN LEAD FREE
 - N:80~120u" MATT TIN LEAD FREE
 - T: 10u"Gold ON CONTACT AREA AND G/F ON SOLDER AREA

CKT	Dim A	Dim B
2	2.0	6.0
3	4.0	8.0
4	6.0	10.0
5	8.0	12.0
6	10.0	14.0
7	12.0	16.0
8	14.0	18.0
9	16.0	20.0
10	18.0	22.0
11	20.0	24.0
12	22.0	26.0
13	24.0	28.0
14	26.0	30.0
15	28.0	32.0
16	30.0	34.0
17	32.0	36.0
18	34.0	38.0
19	36.0	40.0
20	38.0	42.0



CKT	DIM D
2	2.50
OTHER	3.00

QUALITY SYMBOLS MAJOR Ⓢ CRITICAL Ⓢ GENERAL TOLERANCES (UNLESS SPECIFIED) X ±0.5 X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY Lei,shanjun DATE 22/08/24		2.0mm WTB HEADER T/H R/A S/R TYPE	
	CHECKED BY Lu,Jing Quan DATE 22/08/24		APPROVED BY Hsieh,Fu Yu DATE 22/08/24	UNITS mm SCALE 1:1